Product data sheet

1. General description

WG50N65HFW1 uses advanced Fine Trench Field-stop IGBT technology with antiparallel diode in TO247 package to provide extremely low $V_{\text{CE(sat)}}$, and excellent switching performance. This device offers Best-in-Class efficiency in hard switching and resonant topology.



2. Features and benefits

- · Maximum junction temperature 175 °C
- · Positive Temperature efficient for easy paralleling
- · Very soft, fast recovery anti-parallel diode
- · High speed switching
- · EMI Improved Design

3. Applications

- PFC
- Solar converters
- UPS
- Welding Converters
- · Mid to high range switching frequency converters

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Parameter			Value			
V _{CE}	Collector-emitter voltage, T _j ≥ 25 °C			650			V	
I _C	DC collector current, limited by $T_{j(max)}$ $T_C = 100 ^{\circ}C$				50		А	
Symbol	Parameter Conditions		Notes	Min	Тур	Max	Unit	
Static cha	Static characteristics							
V _{CE(sat)}	Collector-emitter saturation voltage	$V_{GE} = 15 \text{ V}; I_{C} = 50 \text{ A}; T_{j} = 25 \text{ °C}$		-	1.55	1.95	V	

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate		•C
2	С	collector		
3	E	emitter		
mb	С	mounting base; connected to collector	TO247	G E sym200

6. Ordering information

Table 3. Ordering information

T	Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
٧	VG50N65HFW1	TO247	WG50N65HFW1Q	Tube	30	SOT429	25-Mar-2013

7. Marking

Table 4. Marking codes

Type number	Marking codes
WG50N65HFW1	G50N65 HFW1

8. Limiting values

Table 5. Limiting values

Symbol	Parameter	Notes	Value	Unit
V _{CE}	Collector-emitter voltage, T _j ≥ 25 °C		650	V
I _C	DC collector current, limited by $T_{j(max)}$ $T_c = 25 ^{\circ}C$ $T_c = 100 ^{\circ}C$		100 50	A
I _{C(puls)}	Pulsed collector current, t _p limited by T _{j(max)}		150	А
-	Turn off safe operating area $V_{CE} \le 650 \text{ V}, T_j \le 175 ^{\circ}\text{C}, t_p = 1 \mu\text{s}$		150	А
l _F	Diode forward current, limited by $T_{j(max)}$ T_{c} = 25 °C T_{c} = 100 °C		100 50	А
I _{Fpuls}	Diode pulsed current, t _p limited by T _{j(max)}		150	Α
V_{GE}	Gate-emitter voltage		±20	V
P _{tot}	Power dissipation $T_C = 25 ^{\circ}\text{C}$ Power dissipation $T_C = 100 ^{\circ}\text{C}$		454 227	W
T _{stg}	Storage temperature		-55 to +150	°C
T_{jmax}	Maximum operating junction temperature		175	°C
-	Peak soldering temperture		260	°C
М	Mounting Torque with washer		0.55	Nm

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
R _{th(j-c)}	IGBT thermal resistance from junction to case			-	0.33	-	K/W
R _{th(j-c)}	Diode thermal resistance from junction to case			-	0.64	-	K/W
R _{th(j-a)}	thermal resistance from junction to ambient			-	40	-	K/W

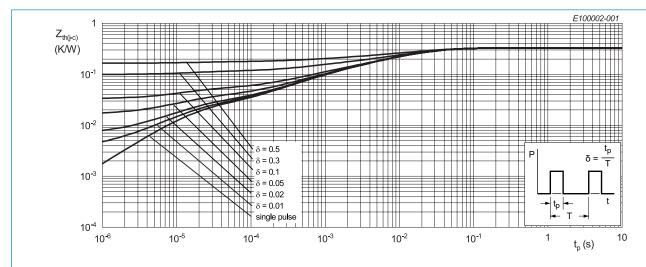


Fig. 1. Transient thermal impedance from junction to case as a function of pulse duration; IGBT

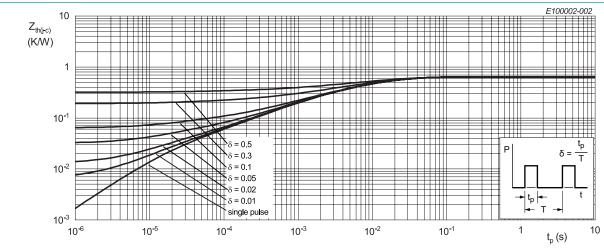


Fig. 2. Transient thermal impedance from junction to case as a function of pulse duration; Diode

10. Characteristics

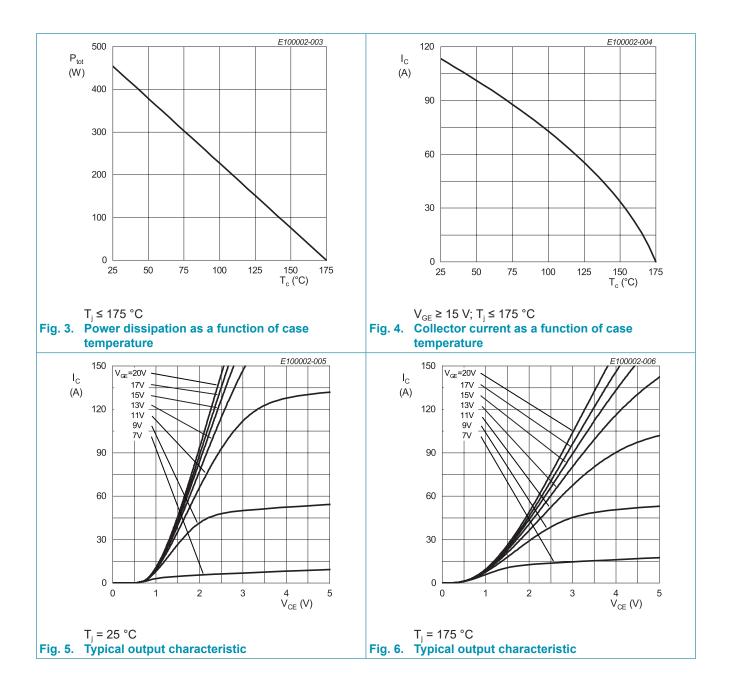
Table 7. Characteristics

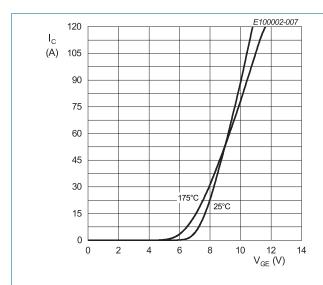
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static cha	racteristics						
BV_CES	Collector-emitter breakdown voltage	$V_{GE} = 0 \text{ V}; I_{C} = 1.0 \text{ mA}$		650	-	-	V
V _{CE(sat)}	Collector-emitter saturation	V_{GE} = 15 V; I_{C} = 50 A; T_{j} = 25 °C		-	1.55	1.95	V
	voltage	V_{GE} = 15 V; I_{C} = 50 A; T_{j} = 175 °C		-	2.1	-	V
V _F	Diode forward voltage	$V_{GE} = 0 \text{ V}; I_F = 50 \text{ A}; T_j = 25 \text{ °C}$		-	2	-	V
		V _{GE} = 0 V; I _F = 50 A; T _j = 175 °C		-	1.6	-	V
$V_{\text{GE(th)}}$	Gate-emitter threhold voltage	$I_{\rm C}$ = 0.5 mA; $V_{\rm CE}$ = $V_{\rm GE}$		4.2	5.2	6.2	V
I _{CES}	Zero gate voltage collector current	$V_{CE} = 650 \text{ V}; V_{GE} = 0 \text{ V}; T_j = 25 \text{ °C}$		-	-	100	μA
		$V_{CE} = 650 \text{ V}; V_{GE} = 0 \text{ V}; T_j = 175 ^{\circ}\text{C}$		-	-	1	mA
g _{fs}	Transconductance	V _{CE} = 20 V; I _C = 50 A		-	34	-	S
Dynamic	characteristics						
C _{ies}	Input capacitance	$V_{CE} = 30 \text{ V}; V_{GE} = 0 \text{ V}; f = 1 \text{ MHz};$		-	2955	-	pF
C _{oes}	Output capacitance	T _j = 25 °C		-	105	-	pF
C _{res}	Reverse transfer capacitance			-	41	-	pF
Q_{G}	Gate charge	V_{CC} = 520 V; I_{C} = 50 A; V_{GE} = 15 V; T_{i} = 25 °C		-	138	-	nC

11. Switching Characteristics

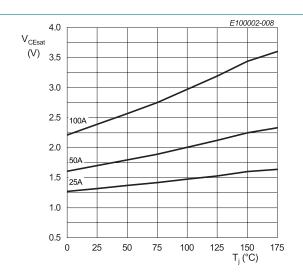
Table 8. Switching Characteristics, Inductive Load

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
IGBT cha	racteristics						
$t_{d(on)}$	Turn-on delay time	T _j = 25 °C;		-	51	-	nS
t _r	Rise time	$V_{CC} = 400 \text{ V}; I_C = 50 \text{ A}; V_{GE} = 15 \text{ V} / 0 \text{ V};$ $R_G = 10 \Omega$		-	51	-	nS
$t_{\text{d(off)}}$	Turn-off delay time			-	198	-	nS
t _f	Fall time			-	28	-	nS
E _{on}	Turn-on energy			-	1.35	-	mJ
E _{off}	Turn-off energy			-	0.65	-	mJ
E _{ts}	Total switching energy			-	2	-	mJ
t _{d(on)}	Turn-on delay time	$T_{\rm j}$ = 175 °C; $V_{\rm CC}$ = 400 V; $I_{\rm C}$ = 50 A; $V_{\rm GE}$ = 15V / 0V; $R_{\rm G}$ = 10 Ω		-	48	-	nS
t _r	Rise time			-	52	-	nS
$t_{d(off)}$	Turn-off delay time			-	226	-	nS
t _f	Fall time			-	39	-	nS
E _{on}	Turn-on energy			-	2.3	-	mJ
E _{off}	Turn-off energy			-	0.85	-	mJ
E _{ts}	Total switching energy			-	3.15	-	mJ
Diode cha	aracteristics		ı				
t _{rr}	Reverse recovery time	T _j = 25 °C;		-	55	-	nS
Q _r	Reverse recovery charge	$V_R = 400 \text{ V}; I_F = 50 \text{ A}; dI_F/dt = 500 \text{A/us}$		-	321	-	nC
I _{RM}	Reverse recovery peak current			-	10	-	А
t _{rr}	Reverse recovery time	T _j = 175 °C;		-	129	-	nS
Q _r	Reverse recovery charge	\dot{V}_{R} = 400 V; I_{F} = 50 A; dI_{F}/dt = 500A/us		-	1662	-	nC
I _{RM}	Reverse recovery peak current			-	23	-	А

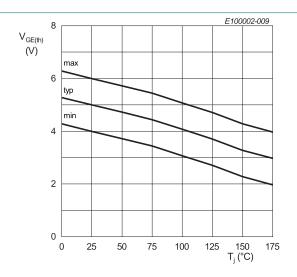




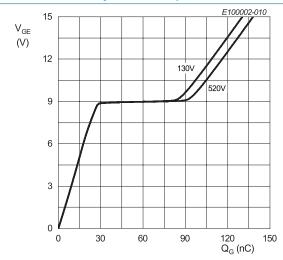
 V_{CE} = 20 V Fig. 7. Typical transfer characteristic



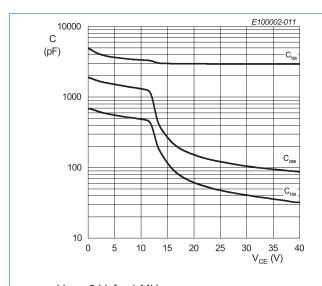
V_{GE} = 15 V
Fig. 8. Typical collector-emitter saturation voltage as a function of junction temperature

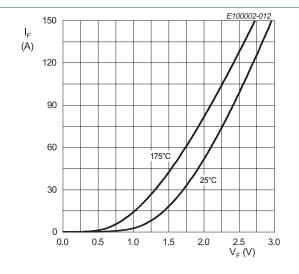


 I_c = 500 μA Fig. 9. Gate-emitter threshold voltage as a function of junction temperature



 $I_c = 50 \text{ A}$ Fig. 10. Typical gate charge

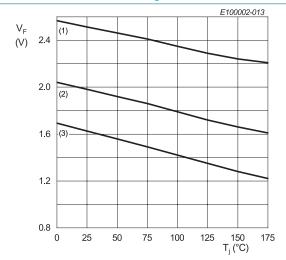


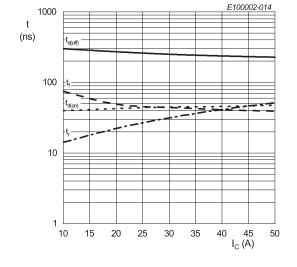


V_{GE} = 0 V; f = 1 MHz

Fig. 12. Typical diode forward current as a function of forward voltage





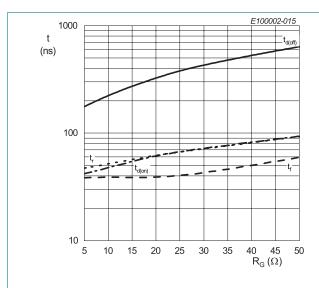


(1) $I_F = 100 \text{ A}$ (2) $I_F = 50 \text{ A}$ (3) $I_F = 25 \text{ A}$

$$\begin{split} R_{g} = 10 ~\Omega; ~V_{GE} = 15 \text{V/OV}; ~T_{j} = 175 ~^{\circ}\text{C}; \\ V_{CE} = 400 ~V; ~inductive~load \end{split}$$

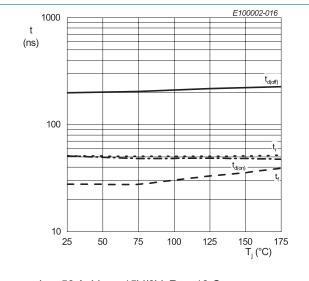
Fig. 13. Typical diode forward voltage as a function of junction temperature

Fig. 14. Typical switching times as a function of collector current



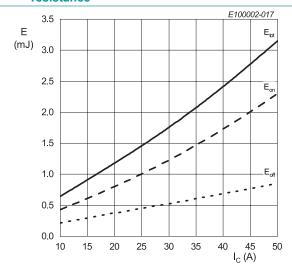
 I_C = 50 A; V_{GE} = 15V/0V; T_j = 175 °C; V_{CE} = 400 V; inductive load

Fig. 15. Typical switching times as a function of gate resistance



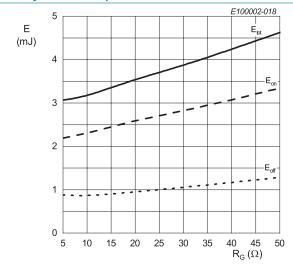
 I_{C} = 50 A; V_{GE} = 15V/0V; R_{g} = 10 Ω ; V_{CE} = 400 V; inductive load

Fig. 16. Typical switching times as a function of junction temperature



 R_g = 10 Ω ; V_{GE} = 15V/0V; T_j = 175 °C; V_{CE} = 400 V; inductive load

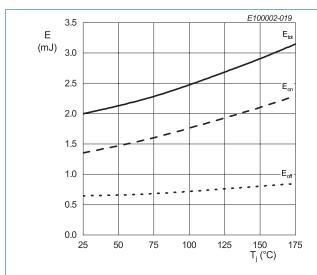
Fig. 17. Typical switching energy losses as a function of collector current



 I_{C} = 50 A; V_{GE} = 15V/0V; T_{j} = 175 °C; V_{CE} = 400 V; inductive load

Fig. 18. Typical switching energy losses as a function of gate resistance

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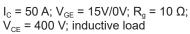


Fig. 20. Forward bias safe operating area



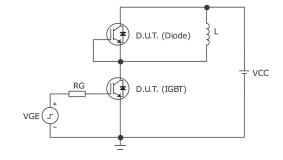


Fig. 21. Test circuit for inductive load switching

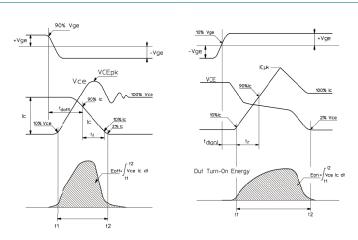
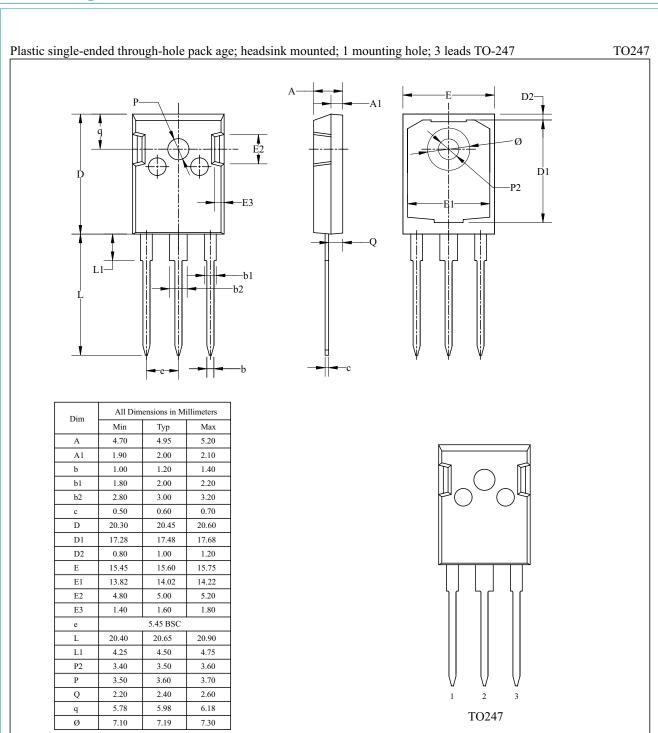


Fig. 22. Definition of switching times and losses

12. Package outline



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13. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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